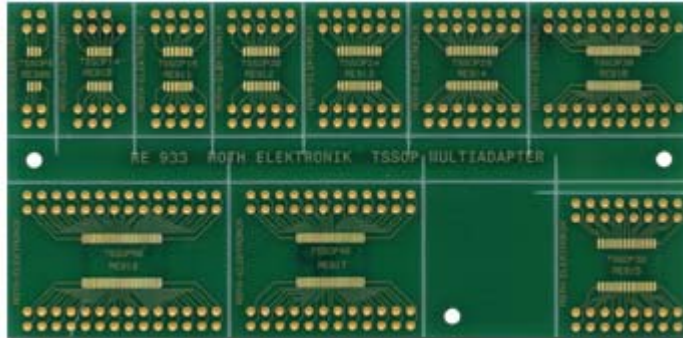




Stock No.: RE933



Stock No.: RE933

TSSOP-SMD Multiadapter (thin shrink small outline package)

- pitch 0,65 mm / 0,50 mm
- FR4 Epoxy fibre-glass 1.50 mm double-sided 35 µm CU
- plated through-holes Ø 1.00 mm
- adapter for 10 different TSSOP

Pitch (mm)	mil	Pin/quantity	body size (mm)
0,65	22,5	8	4,4 (173 mil)
0,65	22,5	14	4,4 (173 mil)
0,65	22,5	16	4,4 (173 mil)
0,65	22,5	20	4,4 (173 mil)
0,65	22,5	24	4,4 (173 mil)
0,65	22,5	28	4,4 (173 mil)
0,65	22,5	32	6,1 (240 mil)
0,50	19,6	38	4,4 (173 mil)
0,50	19,6	48	6,1 (240 mil)
0,50	19,6	56	6,1 (240 mil)

- Solder and component side with chemical gold surface and solder stop mask
- Pre-scratched rated break point for the separation of individual modules from the board
- Size: 58.90 x 120,10 mm